SN65ALS176, SN75ALS176, SN75ALS176A, SN75ALS176B DIFFERENTIAL BUS TRANSCEIVERS

SLLS040H - AUGUST 1987 - REVISED JUNE 2000

- Meet or Exceed the Requirements of TIA/EIA-422-B, TIA/EIA-485-A[†] and ITU Recommendations V.11 and X.27
- Operate at Data Rates up to 35 Mbaud
- Four Skew Limits Available:

SN65ALS176 . . . 15 ns SN75ALS176 . . . 10 ns SN75ALS176A . . . 7.5 ns SN75ALS176B . . . 5 ns

- Designed for Multipoint Transmission on Long Bus Lines in Noisy Environments
- Low Supply-Current Requirements
 ... 30 mA Max
- Wide Positive and Negative Input/Output Bus-Voltage Ranges
- Thermal Shutdown Protection
- Driver Positive and Negative Current Limiting
- Receiver Input Hysteresis
- Glitch-Free Power-Up and Power-Down Protection
- Receiver Open-Circuit Fail-Safe Design

D OR P PACKAGE (TOP VIEW) R 1 8 V_{CC} RE 2 7 B DE 3 6 A D 4 5 GND

description

The SN65ALS176 and SN75ALS176 series differential bus transceivers are designed for bidirectional data communication on multipoint bus transmission lines. They are designed for balanced transmission lines and meet TIA/EIA-422-B, TIA/EIA-485-A, and ITU Recommendations V.11 and X.27.

The SN65ALS176 and SN75ALS176 series combine a 3-state, differential line driver and a differential input line receiver, both of which operate from a single 5-V power supply. The driver and receiver have active-high and active-low enables, respectively, that can be connected together externally to function as a direction control. The driver differential outputs and the receiver differential inputs are connected internally to form a differential input/output (I/O) bus port that is designed to offer minimum loading to the bus when the driver is disabled or $V_{CC} = 0$. This port features wide positive and negative common-mode voltage ranges, making the device suitable for party-line applications.

The SN65ALS176 is characterized for operation from -40° C to 85° C. The SN75ALS176 series is characterized for operation from 0° C to 70° C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

† These devices meet or exceed the requirements of TIA/EIA-485-A, except for the Generator Contention Test (para. 3.4.2) and the Generator Current Limit (para. 3.4.3). The applied test voltage ranges are –6 V to 8 V for the SN75ALS176, SN75ALS176A, and SN75ALS176B and –4 V to 8 V for the SN65ALS180.



AVAILABLE OPTIONS

		PACKAGED	DEVICES
TA	^t sk(lim) [†]	SMALL OUTLINE (D)‡	PLASTIC DIP (P)
0°C to 70°C	10 7.5 5	SN75ALS176D SN75ALS176AD SN75ALS176BD	SN75ALS176P SN75ALS176AP SN75ALS176BP
-40°C to 85°C	15	SN65ALS176D	SN65ALS176P

[†] This is the maximum range that the driver or receiver delay times vary over temperature, V_{CC}, and process (device to device).

Function Tables

DRIVER

INPUT	ENABLE	OUTPUTS	
D	DE	Α	В
Н	Н	Н	L
L	Н	L	Н
Х	L	Z	Z

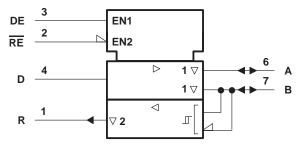
H = high level, L = low level, X = irrelevant, Z = high impedance

RECEIVER

DIFFERENTIAL INPUTS A-B	EN <u>AB</u> LE RE	OUTPUT R
V _{ID} ≥ 0.2 V	L	Н
$-0.2 \text{ V} < \text{V}_{\text{ID}} < 0.2 \text{ V}$	L	?
V _{ID} ≤ -0.2 V	L	L
X	Н	Z
Inputs open	L	Н

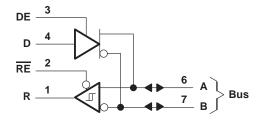
H = high level, L = low level, X = irrelevant, Z = high impedance

logic symbol§



§ This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

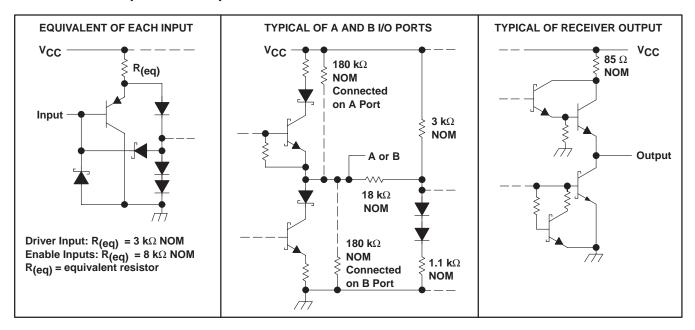
logic diagram (positive logic)



[‡] The D package is available taped and reeled. Add the suffix R to the device type (e.g., SN75ALS176DR).

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schematics of inputs and outputs



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V _{CC} (see Note 1)	
Voltage range at any bus terminal	–7 V to 12 V
Enable input voltage, V _I	5.5 V
Package thermal impedance, θ_{JA} (see Note 2): D package	97°C/W
P package	
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C
Storage temperature range, T _{stq}	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltage values, except differential I/O bus voltage, are with respect to network ground terminal.
 - 2. The package thermal impedance is calculated in accordance with JESD 51.

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recommended operating conditions (unless otherwise noted)

		MIN	NOM	MAX	UNIT
Supply voltage, V _{CC}	4.75	5	5.25	V	
Input voltage at any bus terminal (separately or common mode), V _I or V _{IC}	land to black at any hor target (agreement), an agreement model. More Mar-			12	V
input voltage at any bus terminal (separately of common mode), vpor vpc	_			- 7	V
High-level input voltage, V _{IH}	D, DE, and RE	2			V
Low-level input voltage, V _{IL}	D, DE, and RE			0.8	V
Differential input voltage, V _{ID} (see Note 3)				±12	V
High-level output current, IOH	Driver			-60	mA
riigirievei output current, IOH	Receiver			-400	μΑ
Low lovel output outront les	Driver			60	mA
Low-level output current, IOL Receiver				8	IIIA
Operating free-air temperature, T _A	SN65ALS176	-40		85	°C
Operating free-all temperature, 1 _A	SN75ALS176 series	0		70	

NOTE 3: Differential input/output bus voltage is measured at the noninverting terminal A with respect to the inverting terminal B.



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DRIVER SECTION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEST CO	ONDITIONS†	MIN	TYP‡	MAX	UNIT
٧ıĸ	Input clamp voltage	I _I = -18 mA				-1.5	V
٧o	Output voltage	I _O = 0		0		6	V
V _{OD1}	Differential output voltage	I _O = 0		1.5		6	V
IV _{OD2} I	Differential output voltage	R _L = 100 Ω,	See Figure 1	1/2V _{OD1} or 2§			V
		$R_L = 54 \Omega$,	See Figure 1	1.5	2.5	5	V
V _{OD3}	Differential output voltage	$V_{test} = -7 V to 12 V$,	See Figure 2	1.5		5	V
Δ V _{OD}	Change in magnitude of differential output voltage¶	$R_L = 54 \Omega \text{ or } 100 \Omega,$	See Figure 1			±0.2	V
Voc	Common-mode output voltage	$R_L = 54 \Omega \text{ or } 100 \Omega,$	See Figure 1			3 –1	V
Δ Vocl	Change in magnitude of common-mode output voltage¶	R_L = 54 Ω or 100 Ω ,	See Figure 1			±0.2	V
la.	Output current	Outputs disabled	V _O = 12 V			1	mA
Ю	Output current	(see Note 4)	V _O = -7 V			-0.8	IIIA
lіН	High-level input current	V _I = 2.4 V				20	μΑ
I _{IL}	Low-level input current	V _I = 0.4 V				-400	μΑ
		V _O = -4 V	SN65ALS176			-250	
		V _O = -6 V	SN75ALS176			-250	
los	Short-circuit output current#	V _O = 0				-150	mA
		VO = VCC				250	
		V _O = 8 V				250	
lcc	Supply current	No load	Outputs enabled		23	30	mA
ان	Сарріу Саноні	110 1000	Outputs disabled		19	26	1117

[†] The power-off measurement in TIA/EIA-422-B applies to disabled outputs only and is not applied to combined inputs and outputs.

NOTE 4: This applies for power on and power off. Refer to TIA/EIA-485-A for exact conditions. The TIA/EIA-422-B limit does not apply for a combined driver and receiver terminal.

[‡] All typical values are at $V_{CC} = 5 \text{ V}$ and $T_A = 25^{\circ}\text{C}$.

[§] The minimum V_{OD2} with a 100- Ω load is either 1/2 V_{OD1} or 2 V, whichever is greater.

[¶] Δ |VOD| and Δ |VOC| are the changes in magnitude of VOD and VOC, respectively, that occur when the input is changed from one logic state to the other.

[#] Duration of the short circuit should not exceed one second for this test.

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switching characteristics over recommended ranges of supply voltage and operating free-air temperature range (unless otherwise noted)

SN65ALS176

	PARAMETER		TEST CONDITION	NS	MIN	TYP	MAX	UNIT
t _d (OD)	Differential output delay time	$R_L = 54 \Omega$,	$C_L = 50 pF$,	See Figure 3			15	ns
tsk(p)	Pulse skew [‡]	$R_L = 54 \Omega$,	$C_L = 50 pF$,	See Figure 3		0	2	ns
tsk(lim)	Pulse skew§	$R_L = 54 \Omega$,	$C_L = 50 pF$,	See Figure 3			15	ns
t _t (OD)	Differential output transition time	$R_L = 54 \Omega$,	$C_L = 50 pF$,	See Figure 3		8		ns
tPZH	Output enable time to high level	$R_L = 110 \Omega$,	C _L = 50 pF,	See Figure 4			80	ns
tPZL	Output enable time to low level	$R_L = 110 \Omega$,	C _L = 50 pF,	See Figure 5			30	ns
tPHZ	Output disable time from high level	$R_L = 110 \Omega$,	C _L = 50 pF,	See Figure 4			50	ns
tPLZ	Output disable time from low level	$R_L = 110 \Omega$,	C _L = 50 pF,	See Figure 5			30	ns

[†] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

SN75ALS176, SN75ALS176A, SN75ALS176B

	PARAMETER			TEST CONDITIO	NS	MIN	TYP†	MAX	UNIT
		'ALS176				3	8	13	
td(OD)	Differential output delay time	'ALS176A	$R_L = 54 \Omega$,	$C_L = 50 pF$,	See Figure 3	4	7	11.5	ns
` ′	delay time	'ALS176B]			5	8	10	
tsk(p)	Pulse skew [‡]		$R_L = 54 \Omega$,	$C_L = 50 pF$,	See Figure 3		0	2	ns
		'ALS176						10	
tsk(lim)	Pulse skew§	'ALS176A	$R_L = 54 \Omega$,	$C_L = 50 pF$,	See Figure 3			7.5	ns
		'ALS176B]					5	
t _t (OD)	Differential output transi	tion time	$R_L = 54 \Omega$,	C _L = 50 pF,	See Figure 3		8		ns
^t PZH	Output enable time to hi	gh level	$R_L = 110 \Omega$,	C _L = 50 pF,	See Figure 4		23	50	ns
tPZL	Output enable time to lo	w level	$R_L = 110 \Omega$,	C _L = 50 pF,	See Figure 5		14	20	ns
tPHZ	Output disable time from	n high level	$R_L = 110 \Omega$,	C _L = 50 pF,	See Figure 4		20	35	ns
t _{PLZ}	Output disable time from	n low level	$R_L = 110 \Omega$,	$C_L = 50 \text{ pF},$	See Figure 5		8	17	ns

[†] All typical values are at V_{CC} = 5 V, T_A = 25°C.

SYMBOL EQUIVALENTS

DATA-SHEET PARAMETER	TIA/EIA-422-B	TIA/EIA-485-A
Vo	V _{oa} , V _{ob}	V _{oa} , V _{ob}
IV _{OD1} I	Vo	Vo
IV _{OD2} I	$V_t (R_L = 100 \Omega)$	$V_t (R_L = 54 \Omega)$
IV _{OD3} I	None	V _t (test termination measurement 2)
Δ V _{OD}	$ V_t - \overline{V}_t $	$ V_t - \overline{V}_t $
Voc	V _{os}	V _{os}
∆IVOCI	$ V_{OS} - \overline{V}_{OS} $	$ V_{OS} - \overline{V}_{OS} $
los	I _{sa} , I _{sb}	None
IO	$ I_{xa} , I_{xb} $	l _{ia} , l _{ib}



[‡] Pulse skew is defined as the |tpLH - tpHL| of each channel of the same device.

[§] Skew limit is the maximum difference in propagation delay times between any two channels of any two devices.

[‡] Pulse skew is defined as the |tpLH - tpHL| of each channel of the same device.

[§] Skew limit is the maximum difference in propagation delay times between any two channels of any two devices.

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RECEIVER SECTION

electrical characteristics over recommended ranges of common-mode input voltage, supply voltage, and operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEST C	ONDITIONS	MIN	TYP [†]	MAX	UNIT
V _{IT+}	Positive-going input threshold voltage	$V_0 = 2.7 V$,	$I_{O} = -0.4 \text{ mA}$			0.2	V
V _{IT} _	Negative-going input threshold voltage	$V_0 = 0.5 V$,	I _O = 8 mA	-0.2‡			V
V _{hys}	Hysteresis voltage (V _{IT+} – V _{IT-})				60		mV
VIK	Enable-input clamp voltage	I _I = -18 mA				-1.5	V
Vон	High-level output voltage	V _{ID} = 200 mV, See Figure 6	$I_{OH} = -400 \mu A,$	2.7			٧
VOL	Low-level output voltage	V _{ID} = -200 mV, See Figure 6	$I_{OL} = 8 \text{ mA},$			0.45	V
loz	High-impedance-state output current	V _O = 0.4 V to 2.4 V				±20	μΑ
\/.	Line input surrent	Other input = 0 V	V _I = 12 V			1	A
VI	Line input current	(see Note 5)	V _I = −7 V			-0.8	mA
lιΗ	High-level-enable input current	V _{IH} = 2.7 V				20	μΑ
Ι _Ι L	Low-level-enable input current	V _{IL} = 0.4 V				-100	μΑ
rj	Input resistance			12	20		kΩ
los	Short-circuit output current	V _{ID} = 200 mV,	V _O = 0	-15		-85	mA
loo	Supply ourrent	No load	Outputs enabled		23	30	mΛ
ICC	Зирріу сипені	pply current No load			19	26	mA

[†] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

[‡] The algebraic convention, in which the less positive (more negative) limit is designated minimum, is used in this data sheet for common-mode input voltage and threshold voltage levels only.

NOTE 5: This applies for power on and power off. Refer to TIA/EIA-485-A for exact conditions.

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switching characteristics over recommended ranges of supply voltage and operating free-air temperature range (unless otherwise noted)

SN65ALS176

	PARAMETER	TEST CO	NDITIONS	MIN	TYP [†]	MAX	UNIT
t _{pd}	Propagation time	V _{ID} = −1.5 V to 1.5 V, See Figure 7	C _L = 15 pF,			25	ns
t _{sk(p)}	Pulse skew§	V _{ID} = −1.5 V to 1.5 V, See Figure 7	C _L = 15 pF,		0	2	ns
tsk(lim)	Pulse skew¶	$R_L = 54 \Omega$, See Figure 3	C _L = 50 pF,			15	ns
^t PZH	Output enable time to high level	C _L = 15 pF,	See Figure 8		11	18	ns
tPZL	Output enable time to low level	C _L = 15 pF,	See Figure 8		11	18	ns
^t PHZ	Output disable time from high level	C _L = 15 pF,	See Figure 8			50	ns
tPLZ	Output disable time from low level	C _L = 15 pF,	See Figure 8		•	30	ns

 $[\]overline{\dagger}$ All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

SN75ALS176, SN75ALS176A, SN75ALS176B

	PARAMETER		TEST CO	NDITIONS	MIN	TYP [†]	MAX	UNIT
		'ALS176		0 45 5	9	14	19	
t _{pd}	Propagation time	'ALS176A	V _{ID} = −1.5 V to 1.5 V, See Figure 7	$C_L = 15 pF$,	10.5	14	18	ns
		'ALS176B	Geo riguie r		11.5	13	16.5	
^t sk(p)	Pulse skew‡		$V_{ID} = -1.5 \text{ V to } 1.5 \text{ V},$ See Figure 7	$C_L = 15 pF,$		0	2	ns
		'ALS176		0			10	
tsk(lim)	Pulse skew§	'ALS176A	R_L = 54 Ω, See Figure 3	$C_L = 50 pF$,			7.5	ns
		'ALS176B	Goo r iguro o				5	
tPZH	Output enable time to	high level	C _L = 15 pF,	See Figure 8		7	14	ns
tPZL	Output enable time to	low level	C _L = 15 pF,	See Figure 8		20	35	ns
tPHZ	Output disable time fro	om high level	C _L = 15 pF,	See Figure 8		20	35	ns
tPLZ	Output disable time fro	om low level	C _L = 15 pF,	See Figure 8		8	17	ns

[†] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

PARAMETER MEASUREMENT INFORMATION

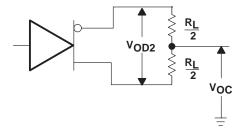


Figure 1. Driver V_{OD2} and V_{OC}



[§] Pulse skew is defined as the |tplH - tpHL| of each channel of the same device.

 $[\]P$ Skew limit is the maximum difference in propagation delay times between any two channels of any two devices.

[‡]Pulse skew is defined as the |tplH - tpHL| of each channel of the same device.

[§] Skew limit is the maximum difference in propagation delay times between any two channels of any two devices.

PARAMETER MEASUREMENT INFORMATION

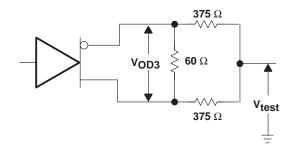
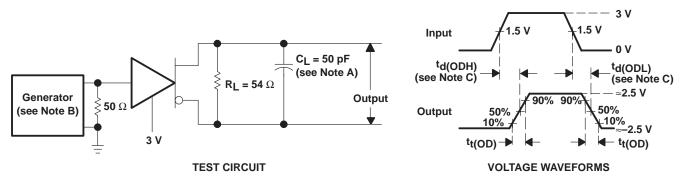
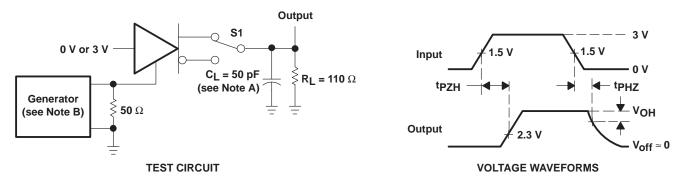


Figure 2. Driver VOD3



- NOTES: A. C_L includes probe and jig capacitance.
 - B. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, 50% duty cycle, $t_r \leq$ 6 ns, $t_f \leq$ 6 ns, $Z_O = 50 \Omega$.
 - C. $t_{d(OD)} = t_{d(ODH)}$ or $t_{d(ODL)}$

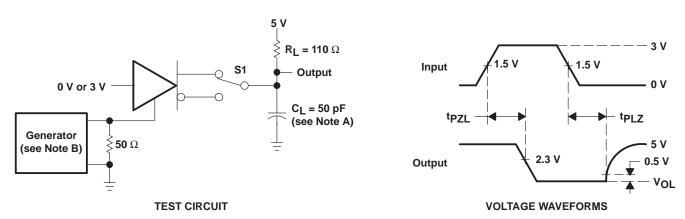
Figure 3. Driver Test Circuit and Voltage Waveforms



- NOTES: A. C_I includes probe and jig capacitance.
 - B. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, 50% duty cycle, $t_{\Gamma} \leq$ 6 ns, $t_{f} \leq$ 6 ns, $t_{O} = 50 \Omega$.

Figure 4. Driver Test Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

B. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, 50% duty cycle, $t_f \leq$ 6 ns, $t_f \leq$ 6 ns, $t_f \leq$ 6 ns, $t_f \leq$ 6 ns, $t_f \leq$ 1 MHz, 50% duty cycle, $t_f \leq$ 1 mHz, $t_$

Figure 5. Driver Test Circuit and Voltage Waveforms

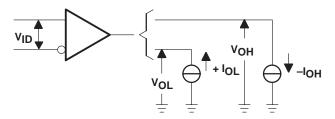
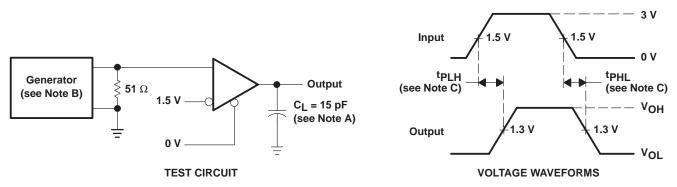


Figure 6. Receiver VOH and VOL Test Circuit



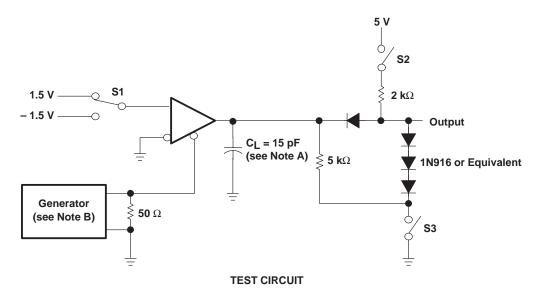
NOTES: A. C_I includes probe and jig capacitance.

- B. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, 50% duty cycle, $t_r \leq$ 6 ns, $t_f \leq$ 6 ns, $Z_O = 50 \Omega$.
- C. $t_{pd} = t_{PLH}$ or t_{PHL}

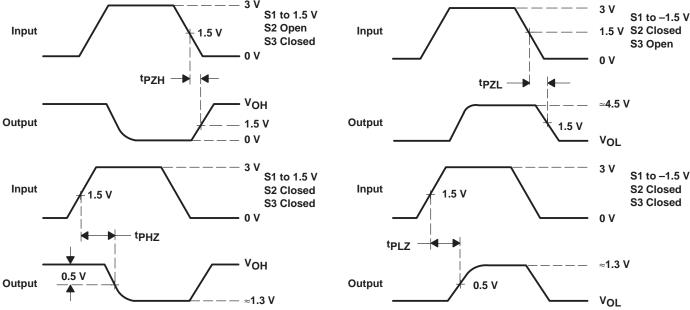
Figure 7. Receiver Test Circuit and Voltage Waveforms



PARAMETER MEASUREMENT INFORMATION







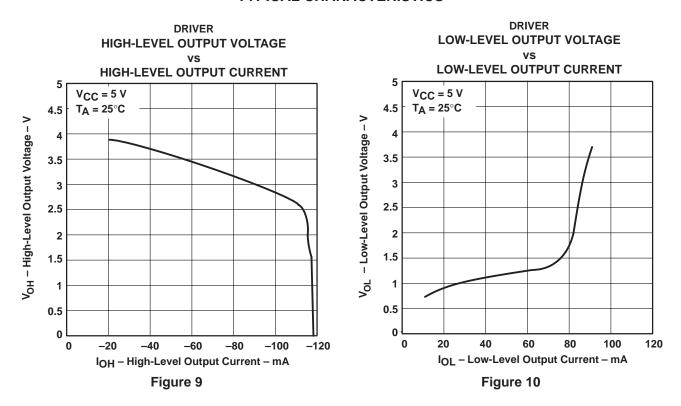
VOLTAGE WAVEFORMS

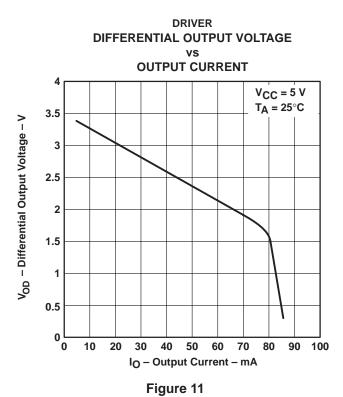
NOTES: A. C_I includes probe and jig capacitance.

B. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, 50% duty cycle, $t_f \leq$ 6 ns, $t_f \leq$ 8 ns, $t_f \leq$ 9 ns

Figure 8. Receiver Test Circuit and Voltage Waveforms

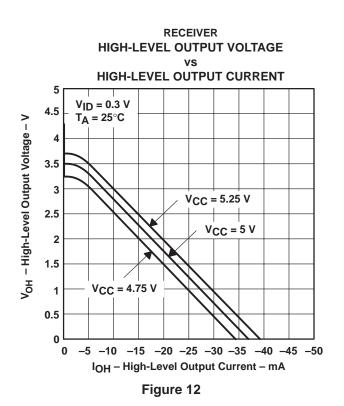
TYPICAL CHARACTERISTICS[†]

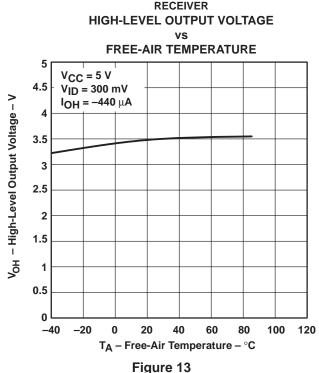


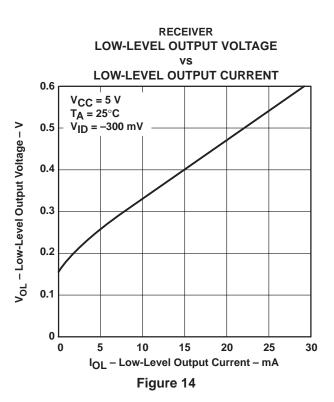


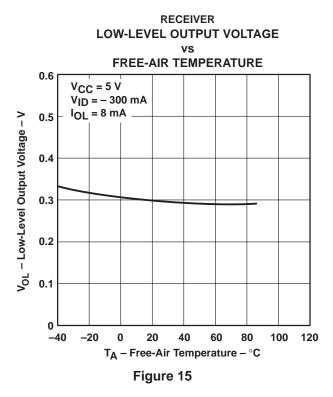
[†] Operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied.

RECEIVER TYPICAL CHARACTERISTICS[†]





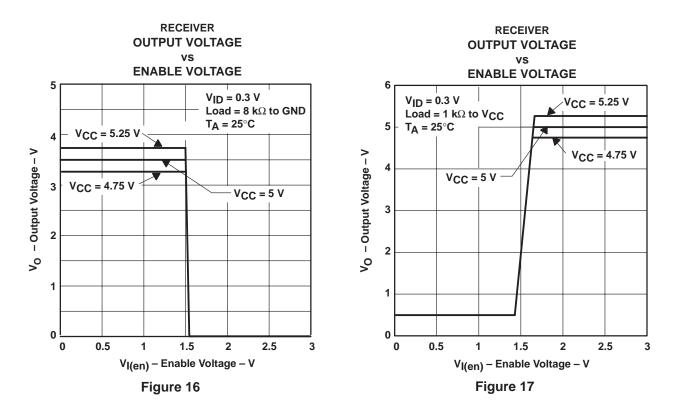




[†] Operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied.

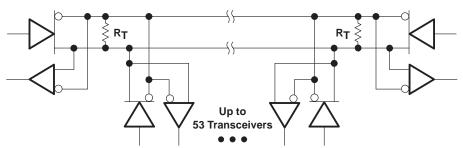


TYPICAL CHARACTERISTICS[†]



[†] Operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied.

APPLICATION INFORMATION



NOTE A: The line should terminate at both ends in its characteristic impedance (R_T = Z_O). Stub lengths off the main line should be kept as short as possible.

Figure 18. Typical Application Circuit



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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Packag Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN65ALS176D	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65ALS176DE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65ALS176DG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65ALS176DR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65ALS176DRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65ALS176DRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65ALS176P	OBSOLETE	PDIP	Р	8		TBD	Call TI	Call TI
SN75ALS176AD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS176ADE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS176ADG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS176ADR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS176ADRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS176ADRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS176AP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN75ALS176APE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN75ALS176BD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS176BDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS176BDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS176BDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS176BDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS176BDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS176BP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN75ALS176BPE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN75ALS176D	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS176DE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM



PACKAGE OPTION ADDENDUM

23-Apr-2007

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN75ALS176DG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS176DR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS176DRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS176DRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS176P	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN75ALS176PE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.



TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN65ALS176DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
SN75ALS176ADR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
SN75ALS176BDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
SN75ALS176DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1



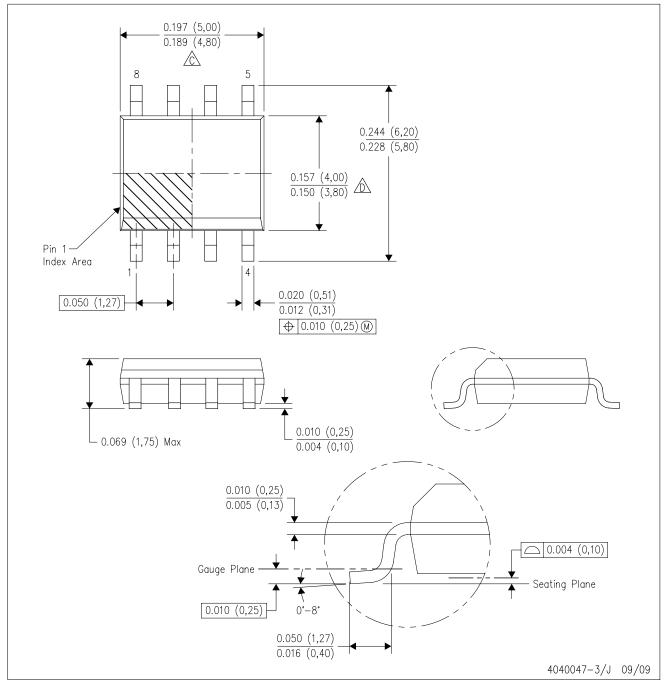


*All dimensions are nominal

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Device	Device Package Type		Pins	SPQ	Length (mm)	Width (mm)	Height (mm)	
SN65ALS176DR	SOIC	D	8	2500	340.5	338.1	20.6	
SN75ALS176ADR	SOIC	D	8	2500	340.5	338.1	20.6	
SN75ALS176BDR	SOIC	D	8	2500	340.5	338.1	20.6	
SN75ALS176DR	SOIC	D	8	2500	340.5	338.1	20.6	

D (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AA.



P (R-PDIP-T8)

PLASTIC DUAL-IN-LINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-001

For the latest package information, go to http://www.ti.com/sc/docs/package/pkg_info.htm





10-Dec-2020

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN65ALS176D	ACTIVE	SOIC	D	8	75	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	65A176	Samples
SN65ALS176DR	ACTIVE	SOIC	D	8	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	65A176	Samples
SN75ALS176AD	ACTIVE	SOIC	D	8	75	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	7A176A	Samples
SN75ALS176ADR	ACTIVE	SOIC	D	8	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	7A176A	Samples
SN75ALS176ADRE4	ACTIVE	SOIC	D	8	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	7A176A	Samples
SN75ALS176ADRG4	ACTIVE	SOIC	D	8	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	7A176A	Samples
SN75ALS176AP	ACTIVE	PDIP	Р	8	50	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	75ALS176A	Samples
SN75ALS176BD	ACTIVE	SOIC	D	8	75	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	7A176B	Samples
SN75ALS176BDG4	ACTIVE	SOIC	D	8	75	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	7A176B	Samples
SN75ALS176BDR	ACTIVE	SOIC	D	8	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	7A176B	Samples
SN75ALS176BP	ACTIVE	PDIP	Р	8	50	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	75ALS176B	Samples
SN75ALS176D	ACTIVE	SOIC	D	8	75	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	75A176	Samples
SN75ALS176DR	ACTIVE	SOIC	D	8	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	75A176	Samples
SN75ALS176P	ACTIVE	PDIP	Р	8	50	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	75ALS176	Samples
SN75ALS176PE4	ACTIVE	PDIP	Р	8	50	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	75ALS176	Samples

⁽¹⁾ The marketing status values are defined as follows: **ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.



PACKAGE OPTION ADDENDUM

10-Dec-2020

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.



TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN65ALS176DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
SN75ALS176ADR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
SN75ALS176BDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
SN75ALS176DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1





*All dimensions are nominal

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Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)	
SN65ALS176DR	SOIC	D	8	2500	340.5	338.1	20.6	
SN75ALS176ADR	SOIC	D	8	2500	340.5	338.1	20.6	
SN75ALS176BDR	SOIC	D	8	2500	340.5	338.1	20.6	
SN75ALS176DR	SOIC	D	8	2500	340.5	338.1	20.6	



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES:

- 1. Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 [0.15] per side.
- 4. This dimension does not include interlead flash.
- 5. Reference JEDEC registration MS-012, variation AA.



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



P (R-PDIP-T8)

PLASTIC DUAL-IN-LINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-001 variation BA.



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